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Progress in the Contactless Capacitive Characterization of Semi-Insulating Substrates

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Outlay

- Objective
- Basics of **C**ontactless **RE**sistivity **MA**pping
- Technical Details
 - COREMA – WT
 - COREMA – RM
 - COREMA – VT
- Measurements
 - Resistivity topography
 - Contactless mobility
 - Activation energy
- Summary



Objective

To provide innovative analytic tools for

- absolute
- rapid
- laterally resolved
- nondestructive
- precise
- low cost

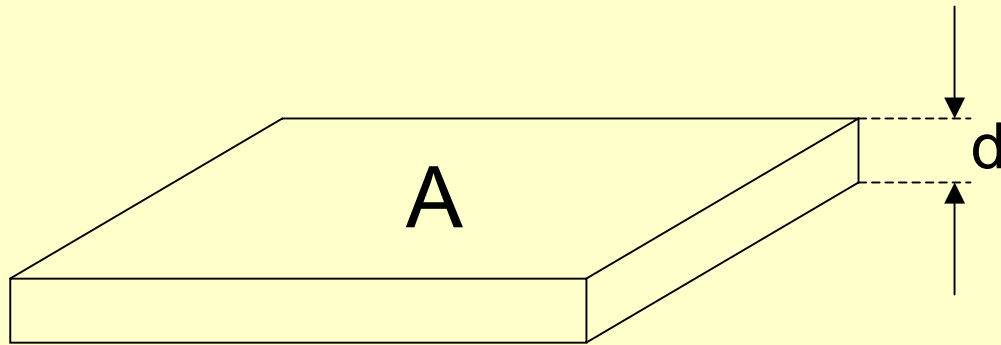
Evaluation of the electrical properties of compound semiconductor substrates for

- production control
- material development



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Basics of **C**ontactless **R**esistivity **M**apping (I)



$$R_s = \rho d/A$$

$$C_s = \varepsilon A/d$$

$$R_s C_s = \rho \varepsilon = \tau$$

Semi-insulating semiconductor

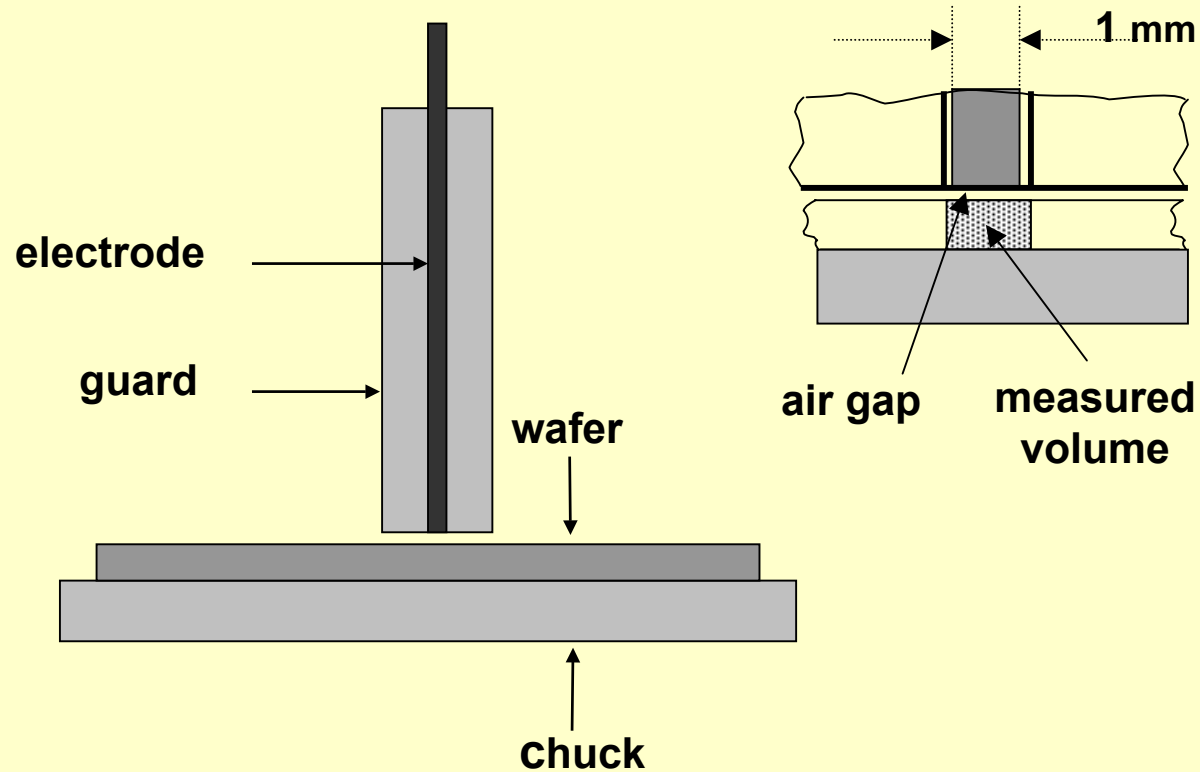
$$\rho = \tau / \varepsilon$$



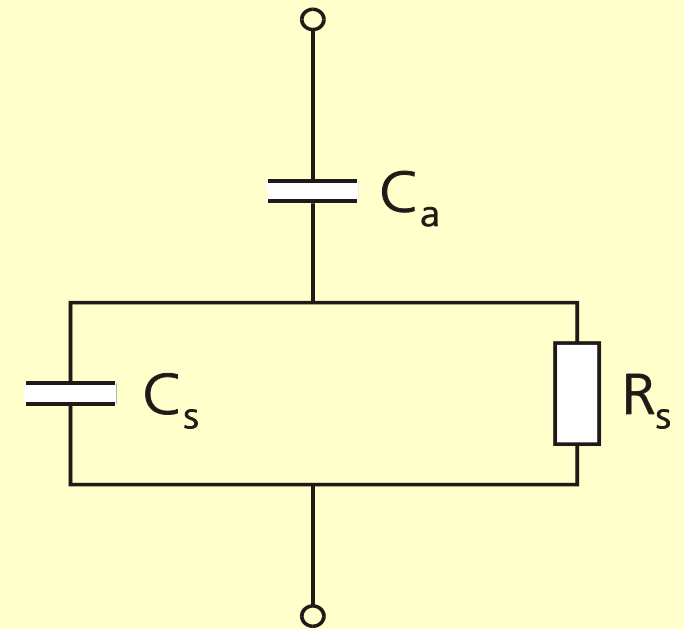
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Basics of **C**ontactless **R**esistivity **M**apping (II)

Capacitive probe



Equivalent circuit

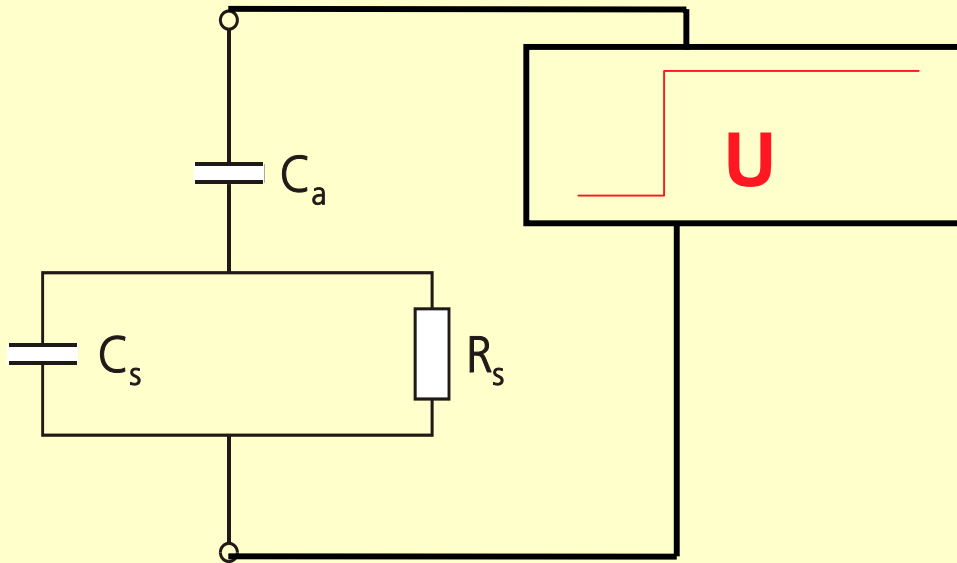


$$\tau = R_s(C_s + C_a)$$



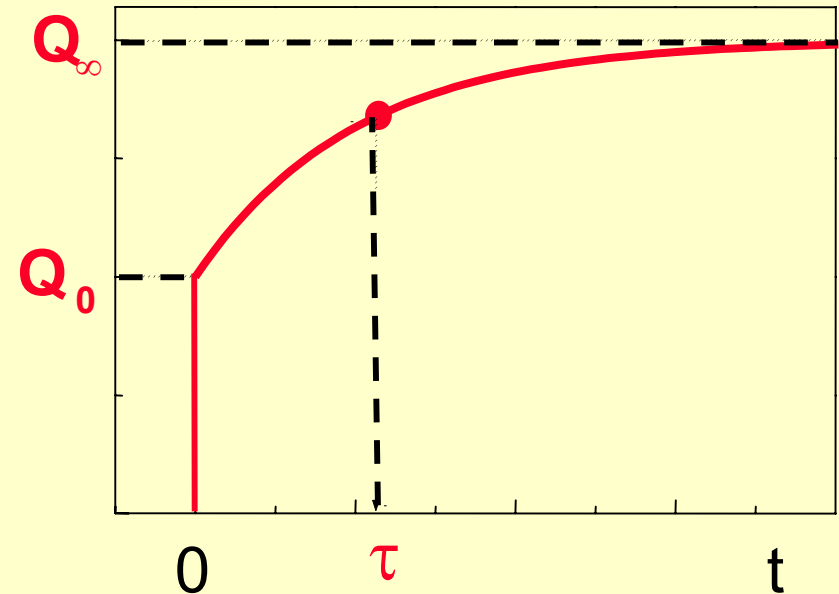
Basics of **C**Ontactless **R**ESistivity **M**APPING (II)

Equivalent circuit



$$\tau = R_s(C_s + C_a)$$

Charge transient after voltage step application



$$\rho = Q_0 \tau (Q_\infty \epsilon \epsilon_0)^{-1}$$



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Basics of **C**Ontactless **R**Esistivity **M**Apping (IV)

Evaluation of electrical material properties

Resistivity

$$\rho = Q_0 \tau (Q_\infty \varepsilon \varepsilon_0)^{-1}$$

Mobility

$$\mu = 1/B [\rho(B) / \rho(0) - 1]^{1/2}$$

Activation energy

$$E_a = (kT_1 T_2) / (T_2 - T_1) * \ln [\rho(T_1) / \rho(T_2)]$$



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Technical Details (I)

COREMA - WT

Specifications

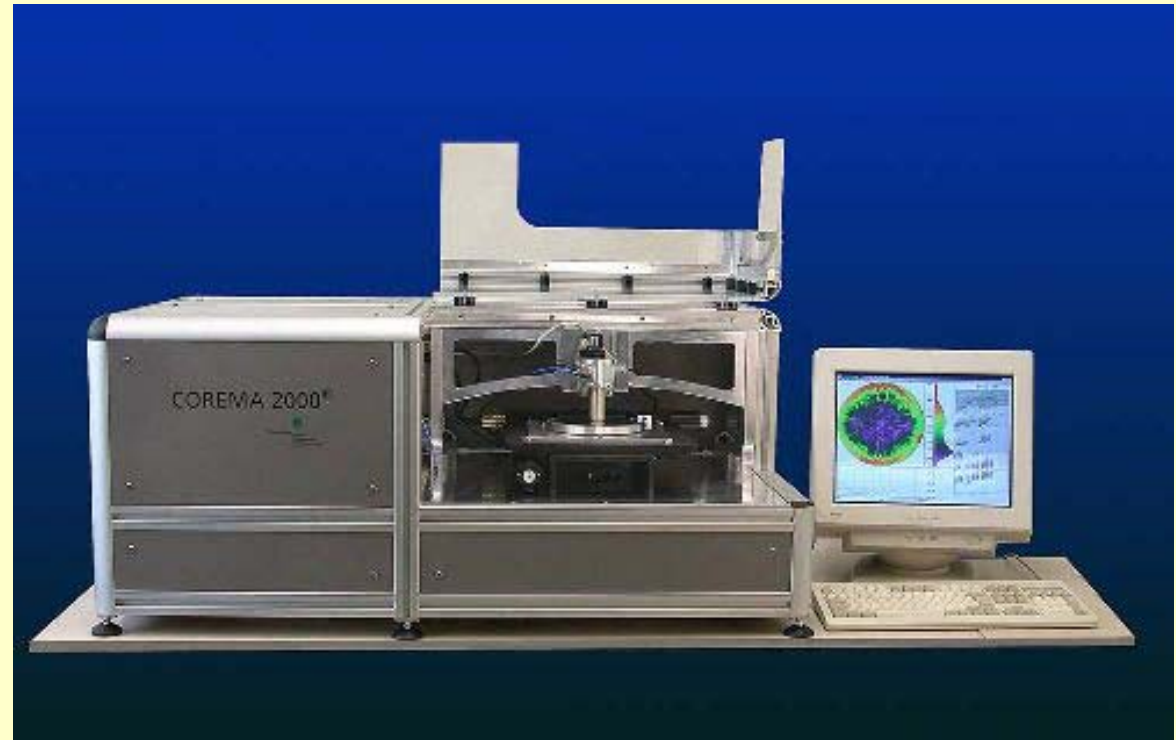
Range $1 \times 10^5 - 1 \times 10^{12} \Omega\text{cm}$

Wafer $\varnothing \leq 200 \text{ mm}$

Probe $\varnothing \leq 1 \text{ mm}$

Repeatability 1%

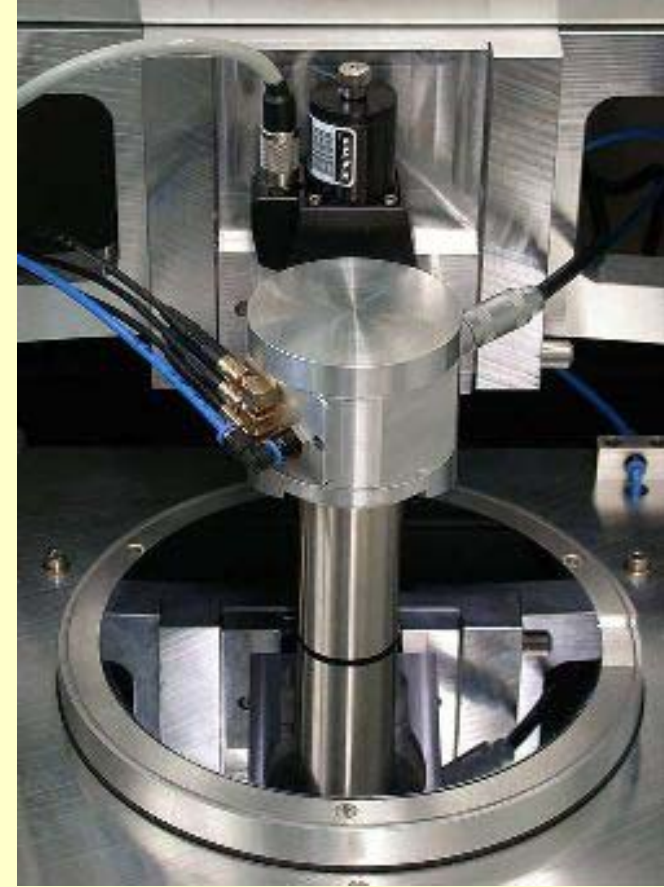
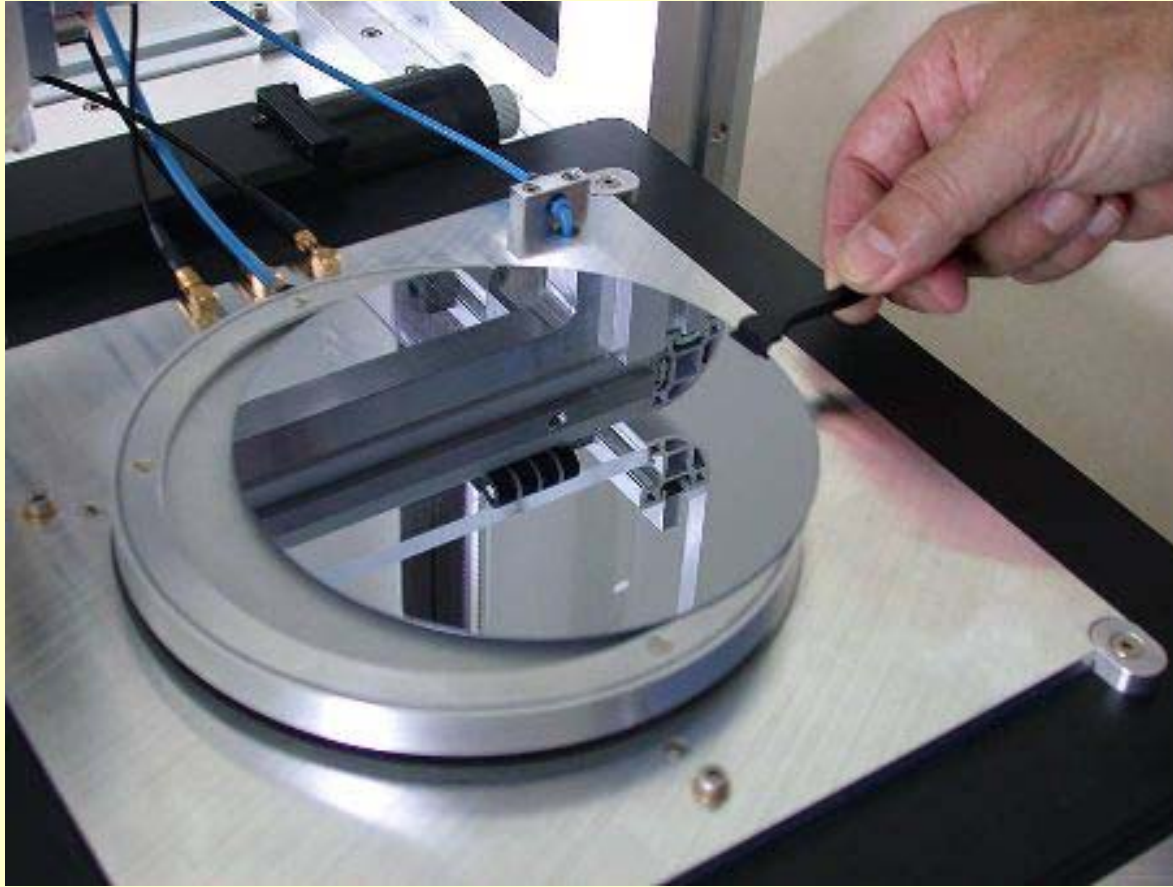
Speed 100 ms @ $1 \text{E}7 \Omega\text{cm}$



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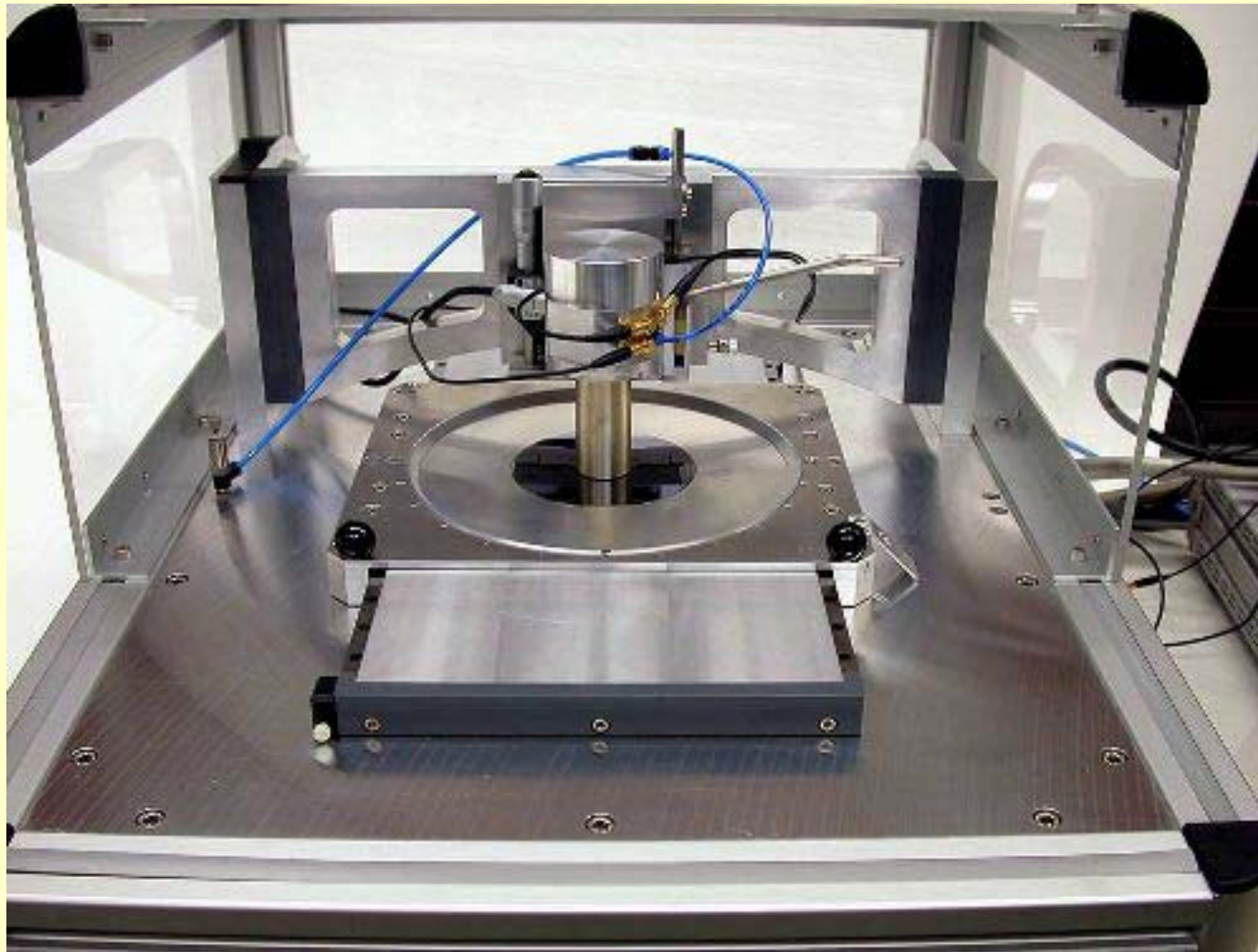
Technical Details (II)

COREMA - WT



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Technical Details (III) **COREMA - RM**



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Technical Details (IV) **COREMA - VT**

System designed to evaluate resistivity at **V**ariable **T**emperature

- Temperature range 300 K – 650 K
- Resistivity range $2 \times 10^5 - 2 \times 10^{11} \Omega\text{cm}$
- High temperature capacitive probe design
- Probe diameter 8 mm
- Sample diameter 10 mm – 100 mm
- Manual loading
- Free choice of measurement position



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Resistivity Topography (I)

GaAs Substrate Production Control

150 mm GaAs wafer

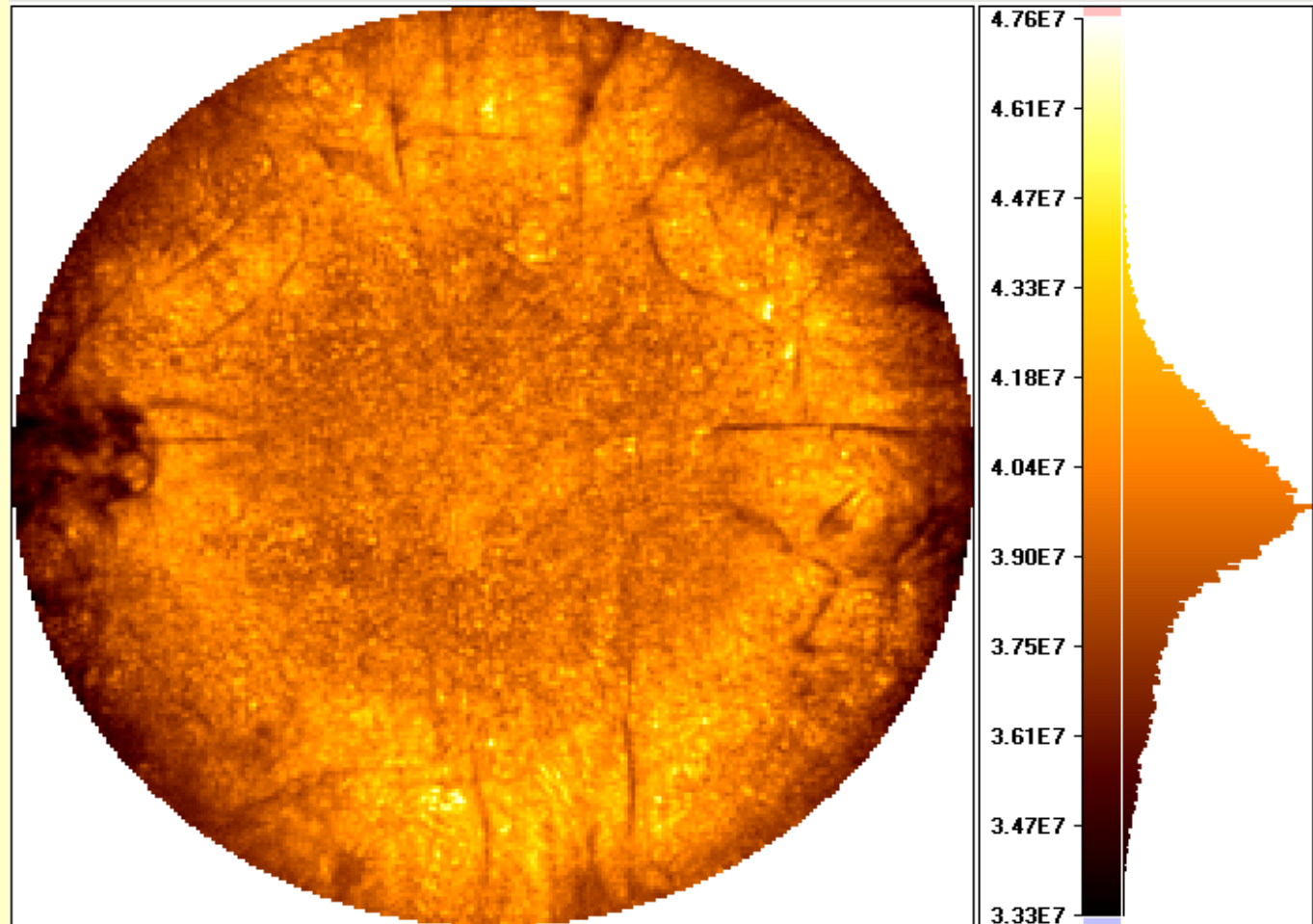
Mean: $3.96 \times 10^7 \Omega \text{ cm}$

Stdv: 4.27 %

Radial variation

Fourfold symmetry

Dislocation network



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Resistivity Topography (II)

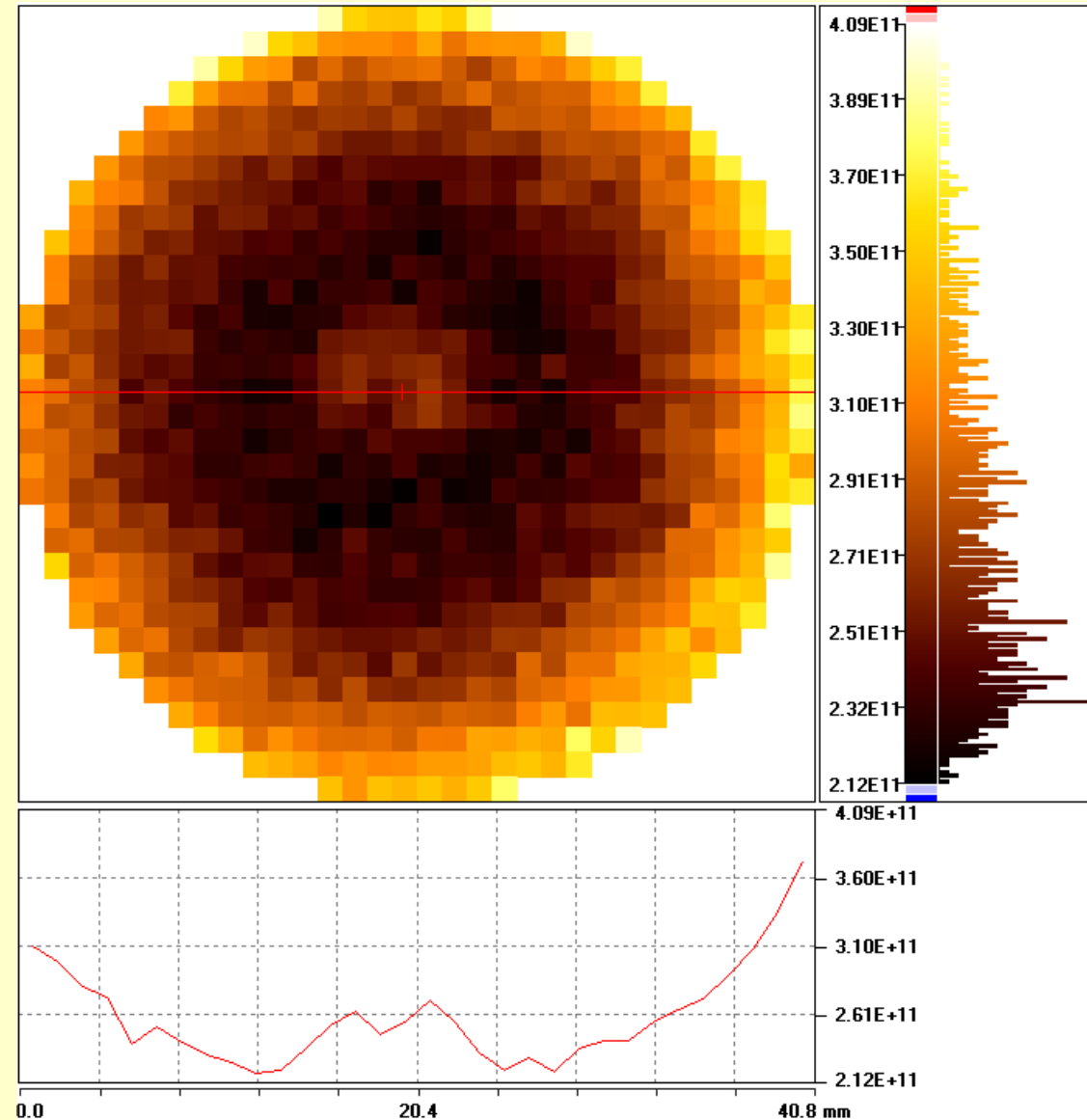
SiC Substrate Production Control

2" SiC Wafer

$2.12 \times 10^{11} - 4.09 \times 10^{11} \Omega\text{cm}$

Mean: $2.75 \times 10^{11} \Omega\text{cm}$

Stdv: 14.7%



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Resistivity Topography (III)

Exploratory SiC Material Development

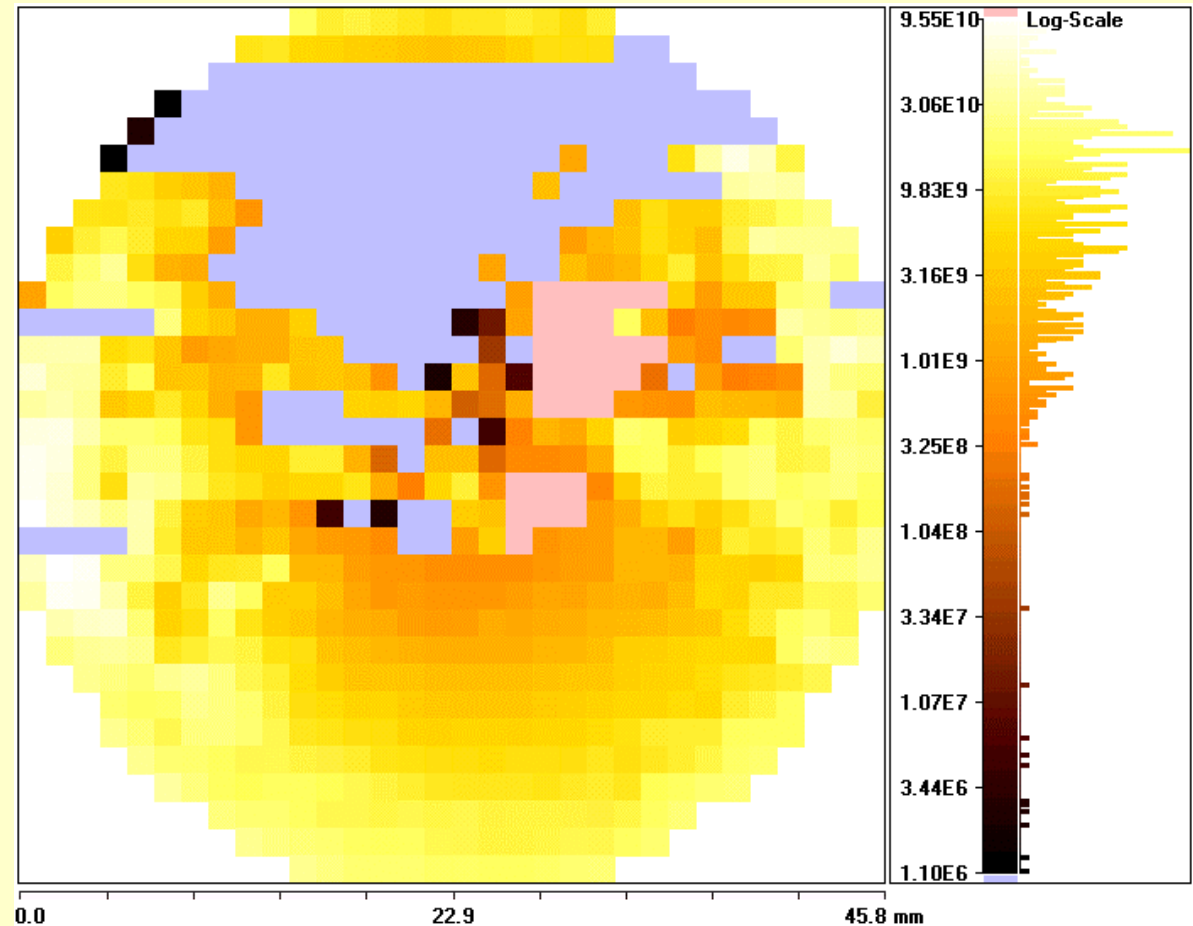
2" SiC wafer

$1.1 \times 10^6 - 1.0 \times 10^{11} \Omega\text{cm}$

Blue area below $10^5 \Omega\text{cm}$

Pink area above $10^{12} \Omega\text{cm}$

Rapid order-of-magnitude
fluctuations



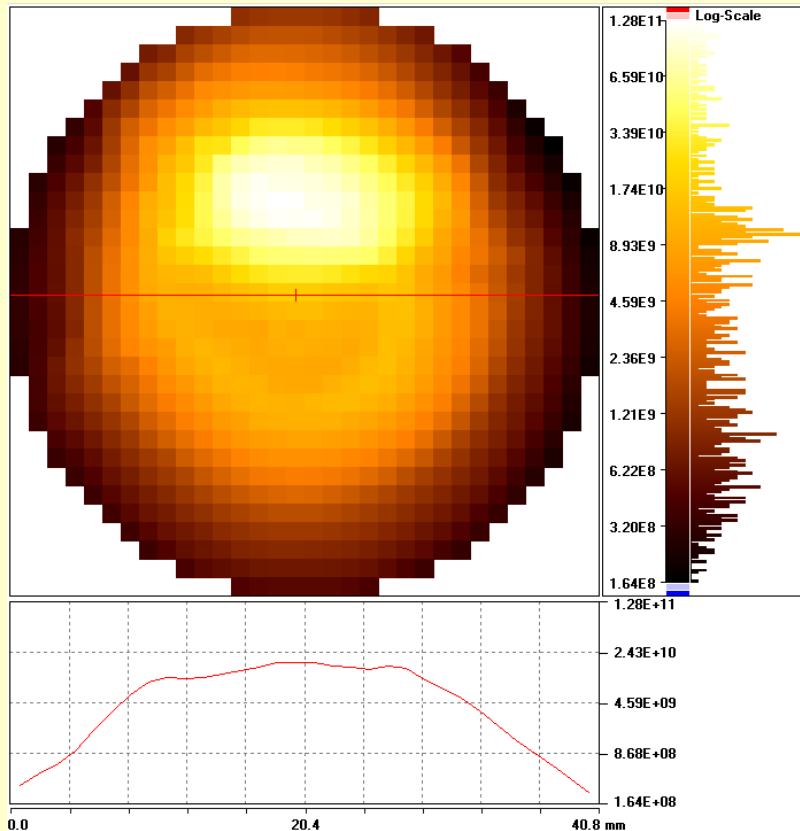
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Resistivity Topography (IV)

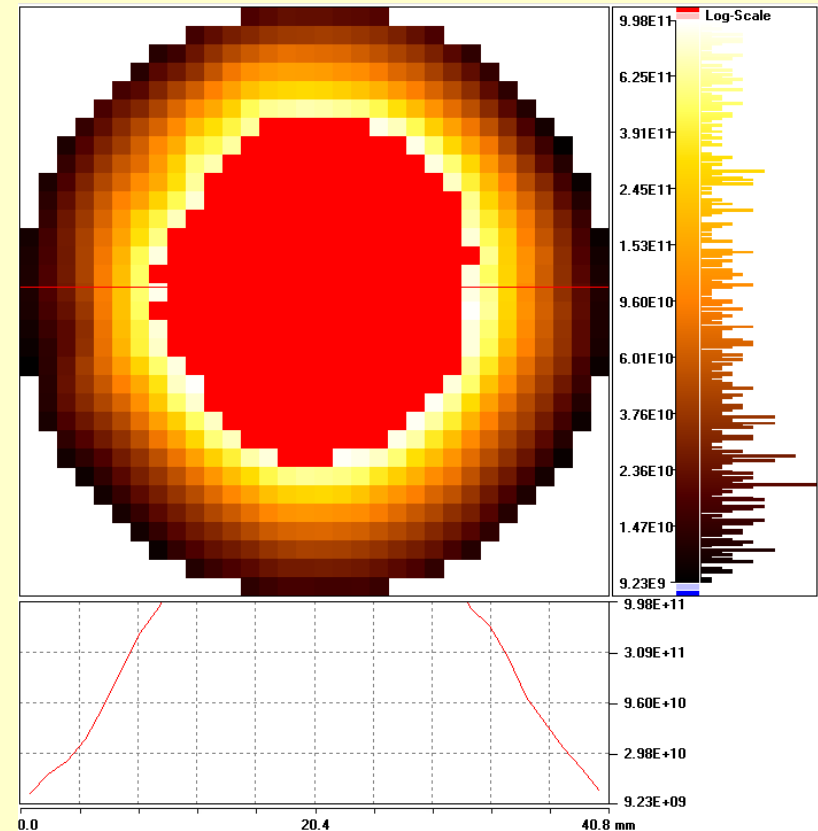
Analysis of Persistent Photoconductivity

Resistivity after 3h storage in darkness

Resistivity after 48h storage in darkness



Mean: $1.12 \times 10^{10} \Omega\text{cm}$



Mean: $1.65 \times 10^{11} \Omega\text{cm}$

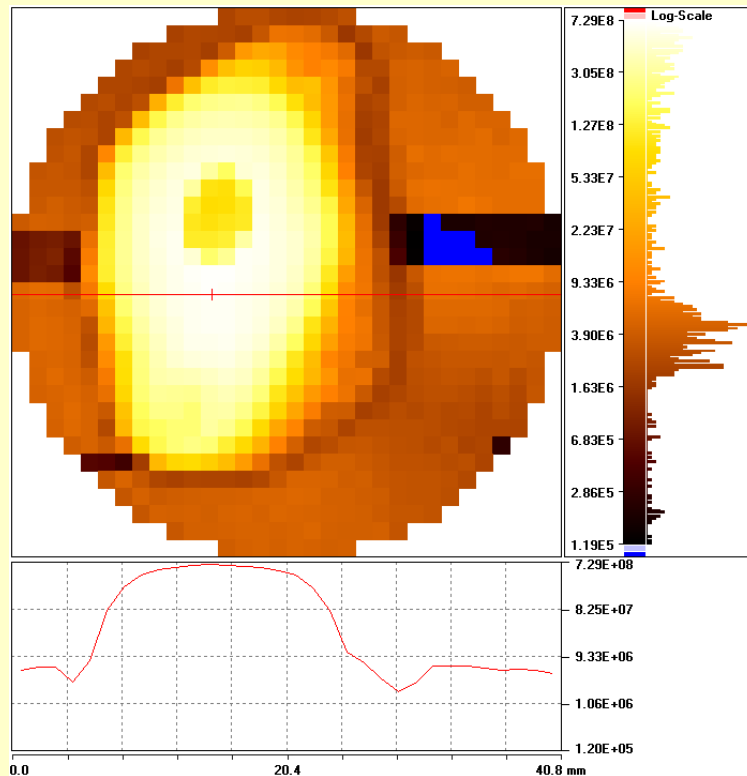


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Resistivity Topography (V)

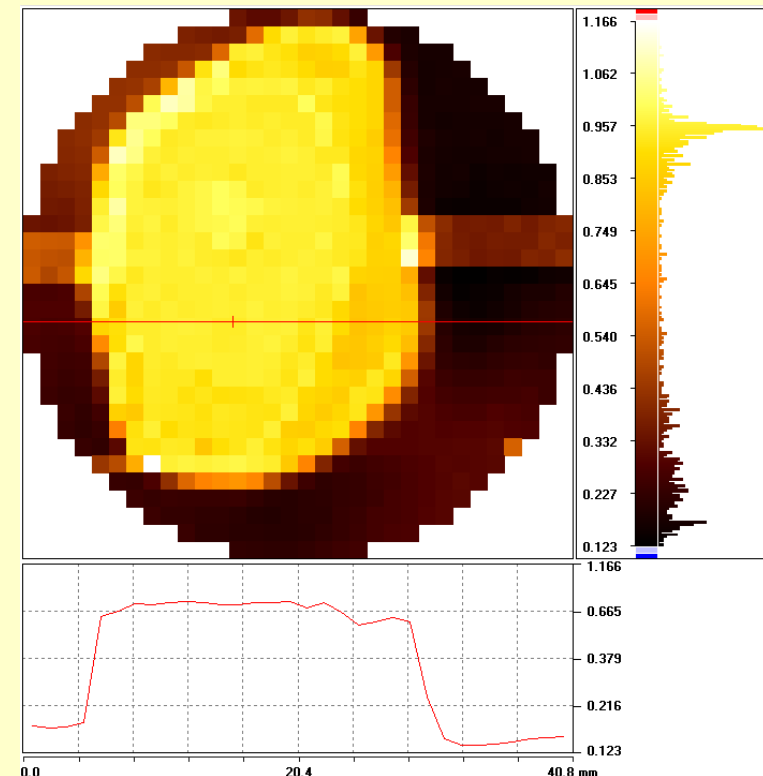
Analysis of locally inhomogeneous Material

Resistivity



Mean: $1.13 \times 10^8 \Omega\text{cm}$
Stdv: 168 %

Volume



Mean: 62%
Stdv: 54%



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Contactless Mobility Measurement (I)

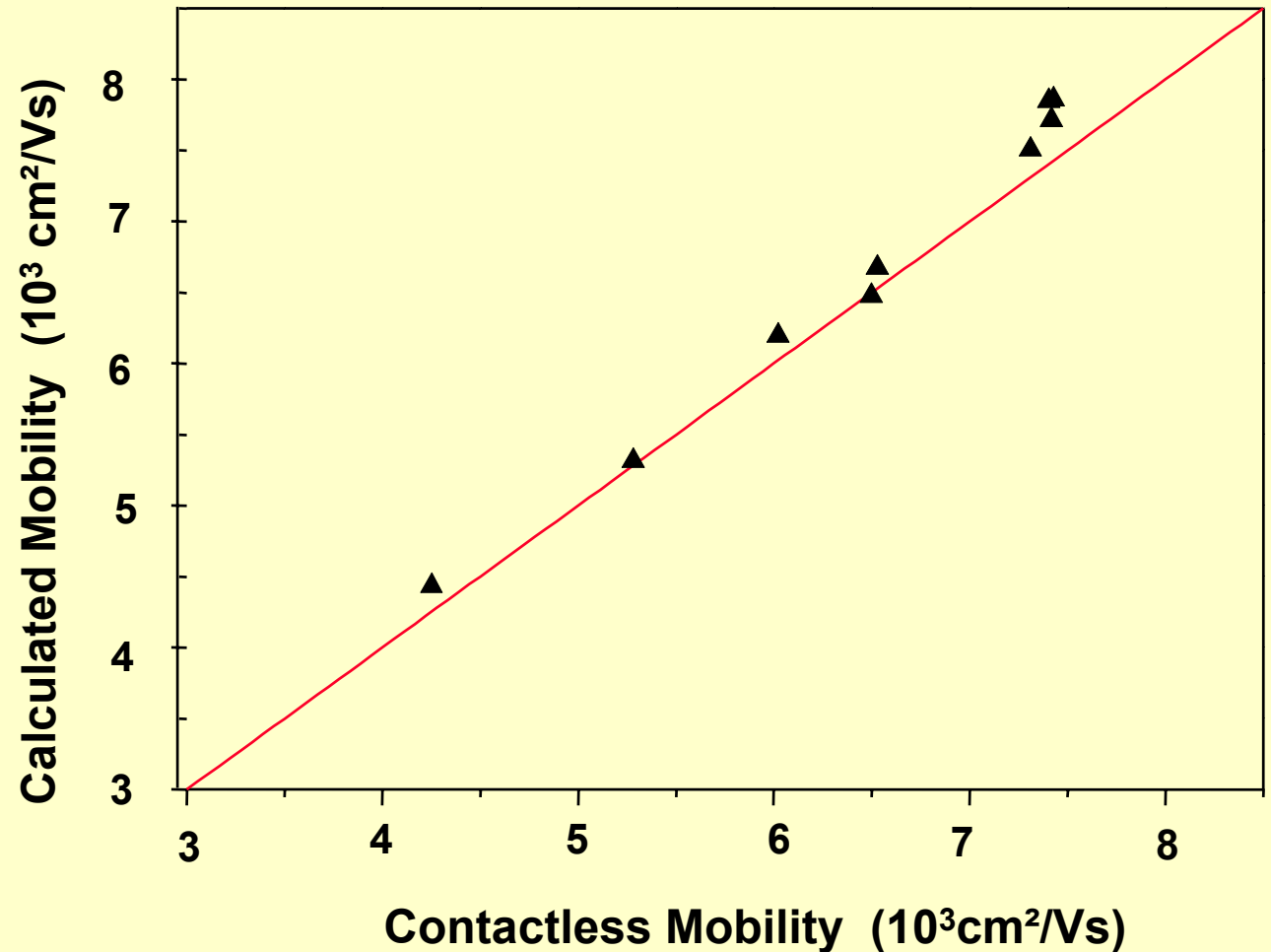
	CONVENTIONAL HALL	COREMA - RM
Wafer cutting	necessary	nondestructive
Ohmic contacts	needed, critical	obsolete
Sample preparation	~ 15 min	none
Sample insertion and measurement time	~ 10 min	~ 30 s
Repeatability	~ 5%	< 1%
Evaluation of SI material	difficult	easy
Applicability	general	SI material only $\mu > 1000 \text{ cm}^2/\text{Vs}$
Acceptance	standard method	new method



Contactless Mobility Measurement (II)

Verification using GaAs samples with different carbon content

Comparison with ionized impurity scattering theory

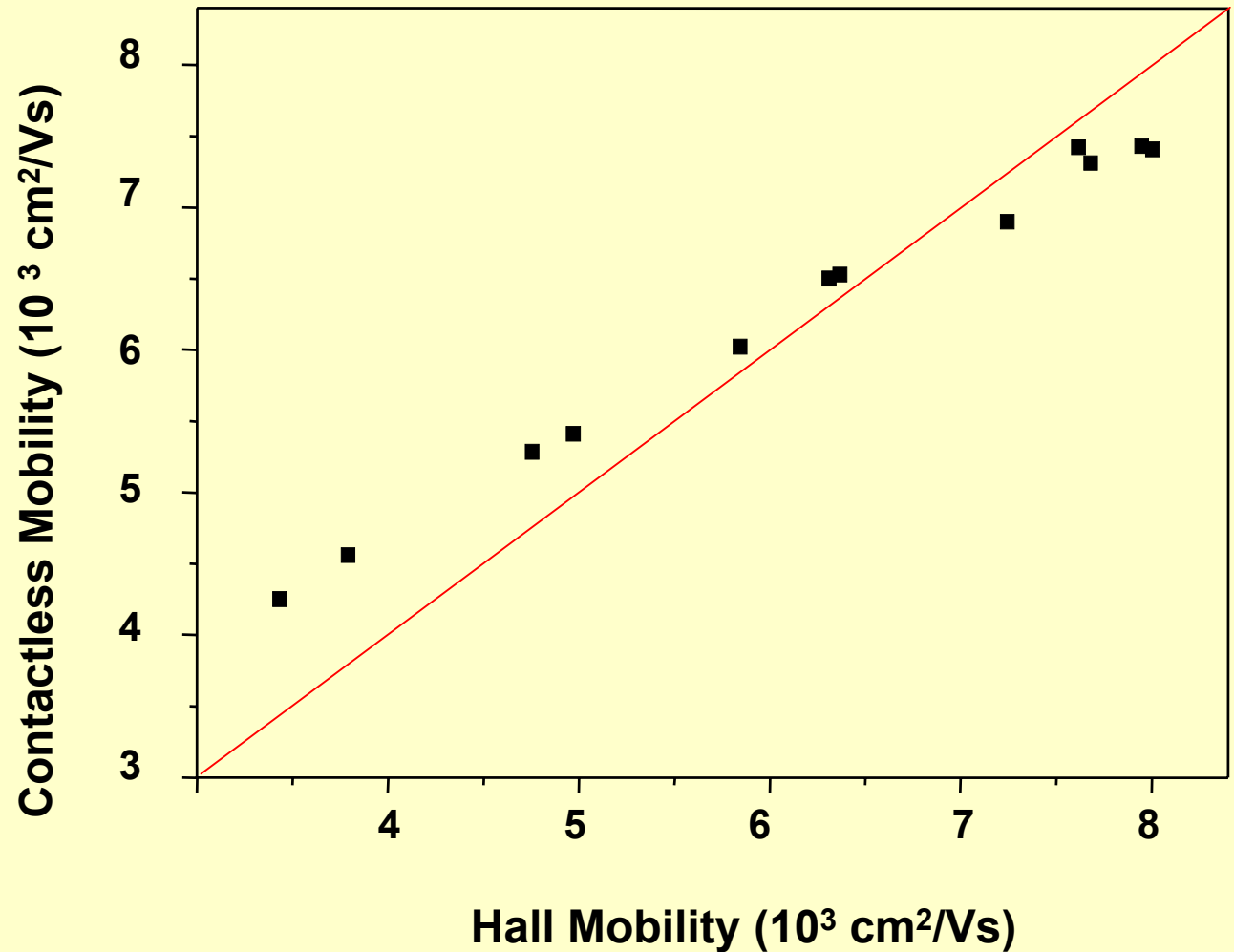


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Contactless Mobility Measurement (III)

Verification using GaAs samples with different carbon content

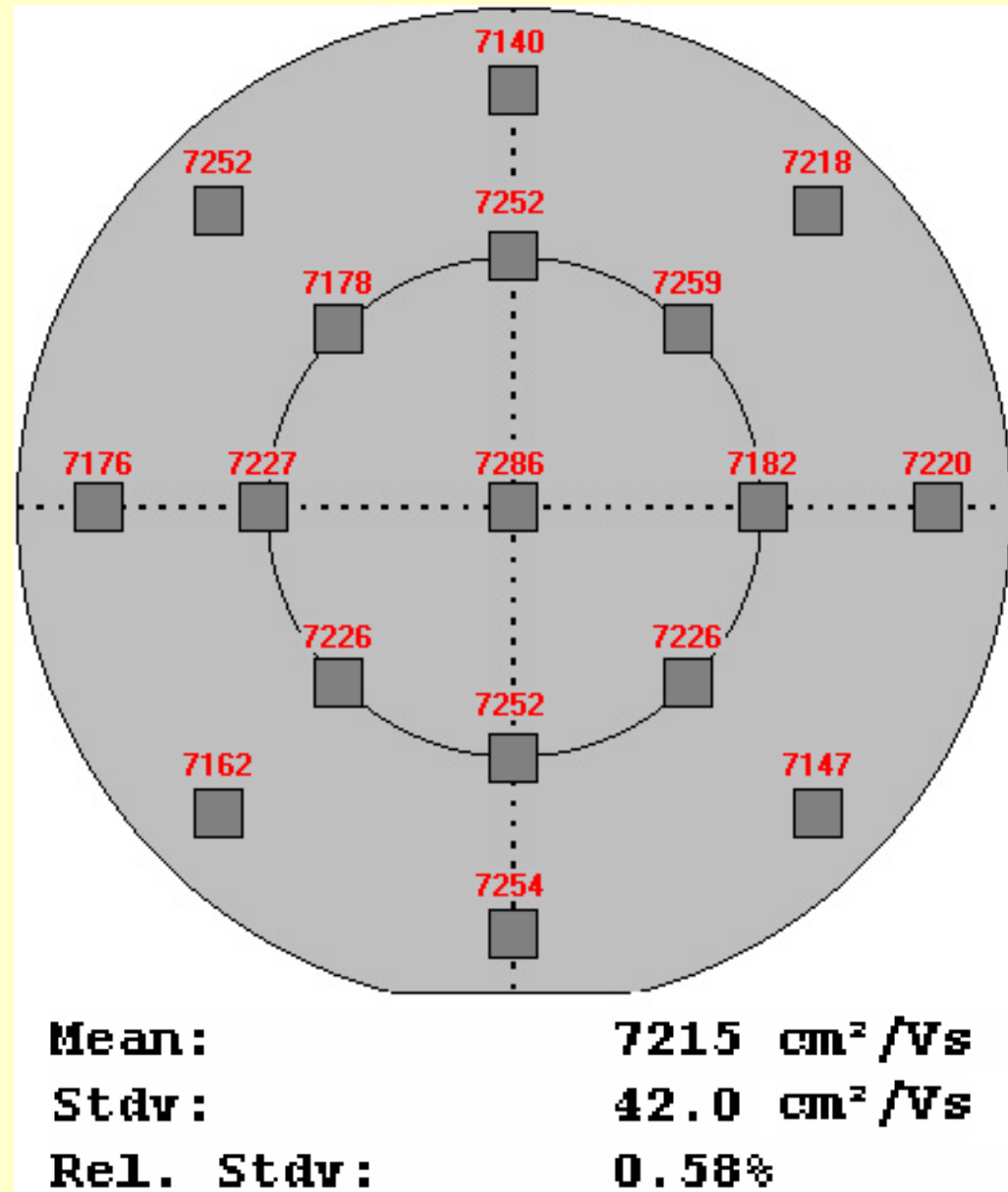
Comparison with Hall data
(sample size 27x27 mm²)



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Contactless Mobility Measurement (IV)

Mobility evaluation using
a customer specified
measurement plan



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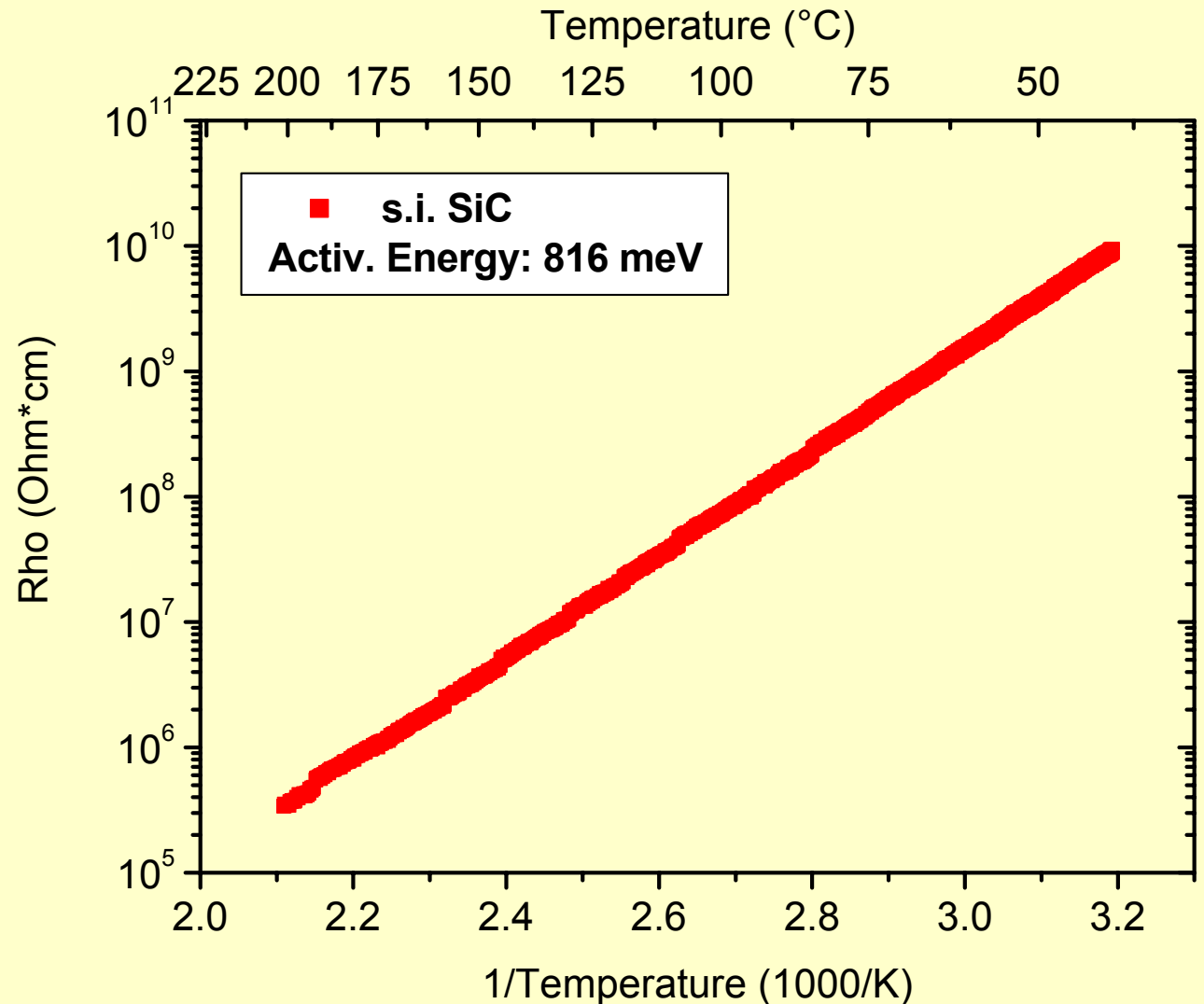
High Temperature Resistivity Measurement (I)

2" SiC wafer

Temperature range
40 – 200 °C

Resistivity range
 $3 \times 10^5 - 1 \times 10^{10} \Omega\text{cm}$

Not semi-insulating
at 300 °C



$$E_a = (kT_1T_2)/(T_2-T_1) * \ln [\rho(T_1) / \rho(T_2)]$$



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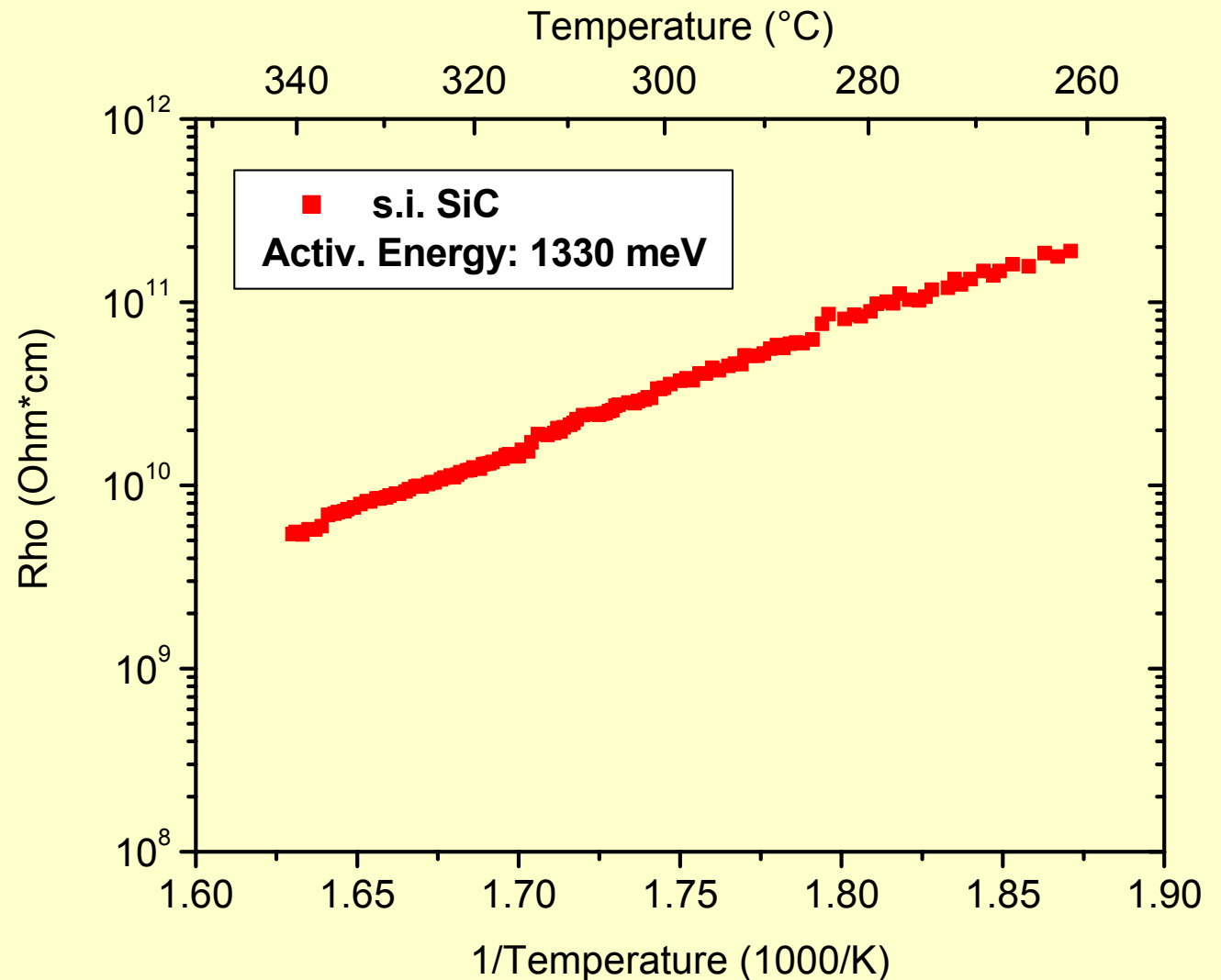
High Temperature Resistivity Measurement (II)

2" SiC wafer

Temperature range
260 – 340 °C

Resistivity range
 $5.6 \times 10^9 - 1.8 \times 10^{11} \Omega\text{cm}$

Semi-insulating at 300 °C



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High Temperature Resistivity Measurement (III)

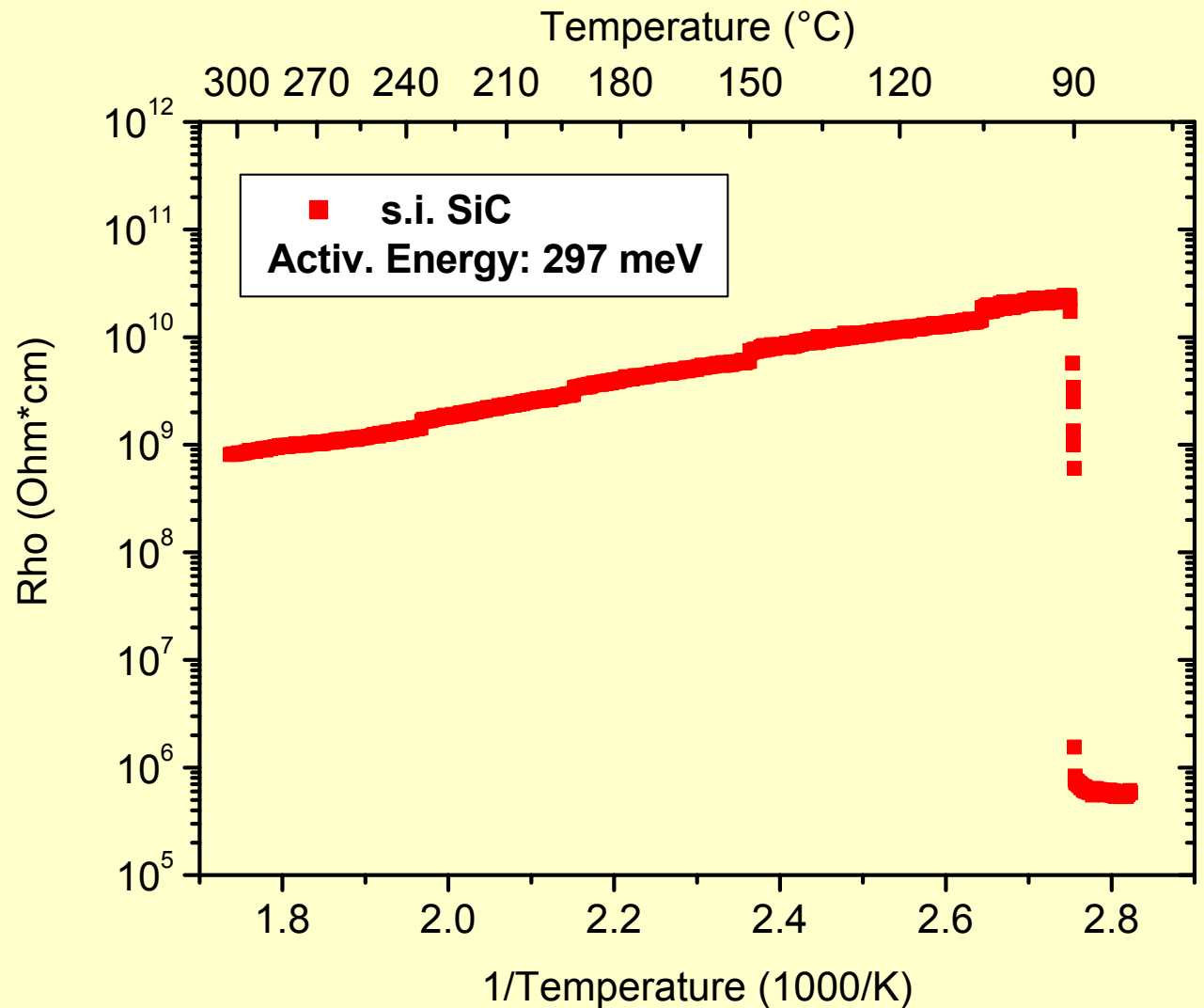
2" SiC wafer

Temperature range
92 – 256 °C

Resistivity range
 $9.0 \times 10^8 - 2.3 \times 10^{10} \Omega\text{cm}$

High resistivity, but small
activation energy

Exhibits strong persistent
photoconductivity



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Summary

- **Automated resistivity topography is used extensively by industry and academia labs for routine wafer quality control and exploratory material analysis of GaAs, InP, SiC, CdT and GaN wafers.**
- **Mobility evaluation based on contactless magnetoresistance has been developed and commercially introduced for rapid, low-cost quality control of GaAs and InP wafers.**
- **A system measuring resistivity at temperatures up to 350 °C has been developed. The activation energy of state-of-the-art and exploratory SiC wafers has been obtained.**

